



100% Material Declaration Data Sheet PQG44

PK208 (v1.0) October 5, 2006

Material Declaration Data Sheet

Average Weight: 0.50052 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.01411	2.81%
	Silicon	7440-21-3	100.00		0.01411	
Die Attach Material					0.00352	0.70%
	Silver	7440-22-4	70.00		0.002467	
	Epoxy (EP)	Trade Secret	20.00		0.000705	
	Anhydride	Trade Secret	10.00		0.000352	
Mold Compound					0.34915	69.67%
	Epoxy Resin (EP)	Trade Secret	15.00		0.052373	
	Silica	60676-86-0	85.00		0.296778	
Leadframe					0.12312	24.57%
	Copper	7440-50-8	98.20		0.118444	
	Nickel	7440-02-0	3.00		0.003694	
	Silicon	7440-21-3	0.65		0.00800	
	Magnesium	7440-95-4	0.15		0.000185	
Leadframe Plating					0.001440	0.29%
	Silver	7440-22-4	100.00		0.001440	
Bond Wire					0.00101	0.20%
	Gold	7440-57-5	100.00		0.00101	
Ext. Plating					0.00817	1.76%
	Tin	7440-31-5	100.00		0.00817	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
10/5/06	1.0	Initial release.